Amphenol®

Application Note

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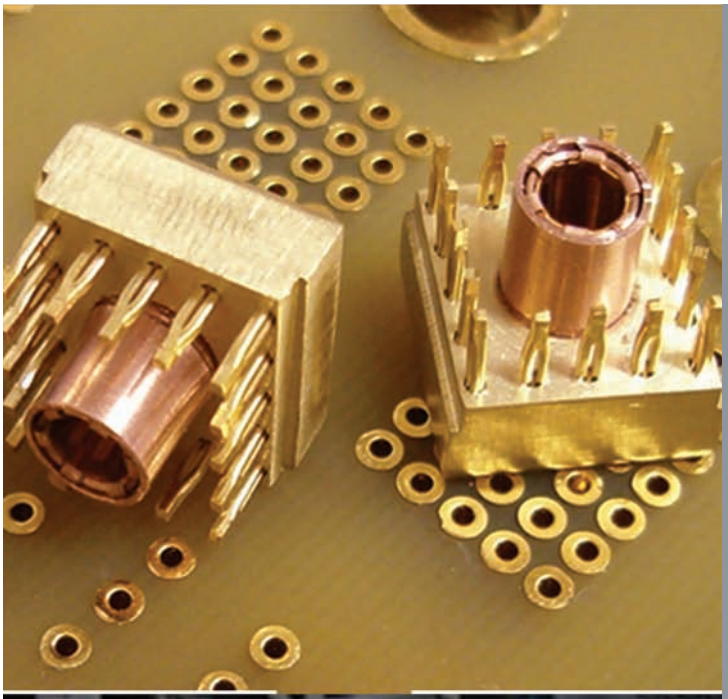

Radsok® PowerBlok

BACKGROUND

Rapidly advancing technology in the Infocom markets are driving vast increases in the levels of “On-Board” power. Infrastructure hardware is transitioning to VoIP and PoE technologies, increasing the need for high amperage power distribution inside the chasis. Designers of these chassis are confronting new challenges to develop easy-to-assemble, reliable, long lifecycle components and assemblies.

PROBLEM

Adding power to existing PCB designs can be achieved by several methods. The most common method to solve the problem is to increase thickness of copper layers. This is expensive and traps heat. Another method is to use wires, but this causes a "rat's nest" which takes up a lot of space and blocks much of the needed air flow.

AIO SOLUTION

The RADSOK® PowerBlok utilizes the industry standard 0.040 compliant pin design. This option is very easily integrated onto the PCB, even late in the design cycle. The power is transferred from the industry proven 3.6mm RADSOK® socket into the compliant pins and into the PCB, in a simple compact package.